

EVASOL J3-EYP-6 *1

Sn-Ag-Cu series
 Lead free resin flux cored wire solder
 Compliant with halogen-free standards of J-STD-709

EVASOL J3-EYP-6 is our product name for Pb-free, flux cored Lead-free wire solder.

Table .Characteristics

Items	Characteristics	Test method
Alloy composition (%)	Sn:Balance, Ag:3.0±0.1, Cu:0.5±0.05	Allowable impurity level is based on JIS Z 3282
Solidus temperature(°C)	217	DSC (Differential Scanning Calorimetry)
Liquidus temperature(°C)	220	
Flux type	ROH1	PIC J-STD-004B
Flux content (mass %)	5.7~6.3	JIS Z 3197 8.1.2
Fluoride contents(mass%)	0.2~0.4	Alfusone method
Halogen content (ppm)	Cl	Less than 500
	Br	Less than 100
		BS EN 14582:2016
Halide content (%)	0.1~0.6	JIS Z 3197 8.1.4.2.1
Copper plate corrosion test	No corrosion	JIS Z 3197 8.4.1
Insulation resistance test(Ω)	More than 1.0×10^7	JIS Z 3197 8.5.3 JIS type, 85°C-85%RH, 168h, measured with DC100V inside of chamber
Migration test	No migration	JIS Z 3197 8.5.4 JIS type, 85°C-85%RH, 1000h, applied with DC48V, visual check
Unit length(m/30g, φ0.15mm) *2	270~330	Calculation from Specific gravity
Valid date	1 year after manufacturing	
Remarks	JIS Z 3282:2006 Solders-Chemical compositions and forms JIS Z 3197:1999 Testing method for soldering fluxes BS EN 14582:2016 Halogen And Sulfur Content. Regulation of substance for J-STD-709 Cl, Br<1000	

*1 J3-EYP-6 is halogen-free flux cored wire solder corresponding to J-STD-709.

*2 Unit length is theoretical value, not guaranteed value.